Nidec

Nidec Advance Technology Corporation

June 03, 2026

Nidec Advance Technology to Exhibit Products at JPCA Show 2026

Nidec Advance Technology Corporation ("Nidec Advance Technology Corporation" or the "Company") announced today that it will exhibit products and solutions at the 55th International Electronic Circuits Exhibition (JPCA Show 2026), to be held at Tokyo International Exhibition Center (Tokyo Big Sight) from Wednesday, June 10 – Friday, June 12, 2026.

This upcoming event will witness Nidec Advance Technology showcase, among other products, an X-ray inspection solution for back drills and EFEM (Equipment Front End Module), a new automatic carrier machine born out of synergies in the Nidec Group. Also featured will be AURCA Series, next-generation AI visual inspection equipment for optical modules and large-size substrates – a product that reflects the latest market trends.

Together with its increasingly accurate existing image and electrical inspection equipment, the company will offer its total inspection solutions to meet the level of quality required of cutting-edge products.

About JPCA Show 2026:
- Period: Wednesday, June 10 – Friday, June 12, 2026
- Venue: East Exhibition Hall, Tokyo International Exhibition Center (Tokyo Big Sight)
- Booth: 3F-33, East 1-2 Hall
- Official website: https://www.jpcashow.com/show2026/

Nidec Advance Technology's exhibits will include:
- High-accuracy inspection solution for TGV (Through Glass Via)
- High-speed, CT-type X-ray machine for back drills
- Equipment Front End Module – automatic carrier machine for full-size and other panels (EFEM Series)
- High-accuracy inspection equipment for large-size single-piece semiconductor packages (GATS®-7837)
- Full-panel substrate inspection equipment for semiconductor package imposition (GATS®-8370)
- Conduction and insulation inspection equipment for large-size/multi-pin substrates (STAR REC® V6)
- Next-generation AI visual inspection equipment for optical modules and large-size substrates (AURCA Series)
- 2D/3D inspection equipment for high-density substrate (RSH Series)
- Probe for narrow pitch (NS probe)
- Power semiconductor die/device inspection system (NATS® Series)

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